

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6968910

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YONG YANG	10/11/2021
XIAOHONG ZHOU	10/11/2021
EVGENY VOVK	10/11/2021
RECEIVING PARTY DATA	
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Street Address:	NO. 393, MIDDLE HUAXIA ROAD, PUDONG DISTRICT
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State/Country:	CHINA
Postal Code:	201210
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17367526
CORRESPONDENCE DATA	
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NAME OF SUBMITTER:	TIANHUA GU
SIGNATURE:	/TIANHUA GU/
DATE SIGNED:	10/14/2021
Total Attachments: 1 source=GUH-451ASSIGN#page1.tif	

ASSIGNMENT

GUH-451

WHEREAS, I/WE:

YANG, Yong; ZHOU, Xiaohong; Evgeny VOVK; ZHAO, Jiafeng, residing in No. 393, Middle Huaxia Road, Pudong District, Shanghai-201210, China

have invented certain new and useful improvements in the following:

AN IN-SITU TEMPERATURE CONTROLLING SAMPLE STAGE CUSTOMIZED FOR COUPLED INTERCONNECTION BETWEEN IN-SITU HIGH-PRESSURE REACTION CELL AND ULTRAHIGH VACUUM CHARACTERIZATION

for which a United States patent application therefor has been executed on 10/11/2021, U.S. Patent Application No.: 17/367526;

WHEREAS,

ShanghaiTech University;

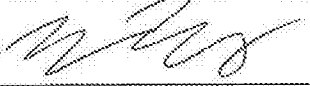
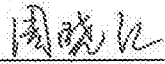
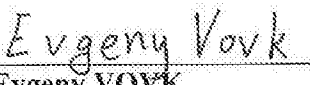
(hereinafter referred to as the Assignee), residing at No. 393, Middle Huaxia Road, Pudong District, Shanghai-201210, China desires to acquire the entire right, title and interest in said application and invention, and to any United States and foreign patents to be obtained therefor.

NOW THEREFORE, for a valuable consideration, receipt whereof is hereby acknowledged, I/we, the above named, hereby sell, assign, and transfer to Assignee, its successors and assigns, the entire right, title and interest in said application and inventions therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said application, I/we hereby agree that Assignee may apply for foreign Letters Patent on said inventions, and I/we hereby agree to timely execute all papers necessary in connection with said United States and foreign Letters Patent applications when called upon to do so by Assignee.

I/we hereby covenant that I/we have the full and lawful right to convey the entire right, title, and interest herein assigned, and that I/we have not entered and will not enter into any agreement in conflict herewith.

I/we hereby request the Commissioner for Patents to issue any Letters Patent granted upon the inventions set forth in said application to Assignee, its successors and assigns.

ASSIGNOR SIGNATURE(S)

	<u>10.11.2021</u>		<u>10.11.2021</u>
YANG, Yong	Date	ZHOU, Xiaohong	Date
	<u>10/11/2021</u>		
Evgeny VOVK	Date	ZHAO, Jiafeng	Date